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Analysis of Wire Bonding Pull-off/Shear Force for Various Wire Materials and Contact Pads

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Abstract. In this paper we study wire contacts made of varied materials (Ag, Au, Cu) and microwelding methods at contact pads with different coatings — immersion gold, galvanic gold, galvanic silver. We present the results of bonding pull-off/shear force testing and compare results of various wire contacts technological operation.

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